



Microwave Ceramics

Series/Type: A760

The following products presented in this data sheet are being withdrawn.

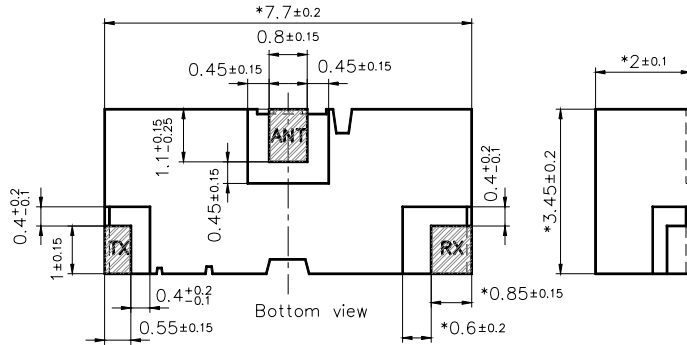
| Ordering Code | Substitute Product | Date of Withdrawal | Deadline Last Orders | Last Shipments |
|-----------------|--------------------|--------------------|----------------------|----------------|
| B69967N2047A760 | B39212B7646B310 | 2008-01-25 | 2008-09-30 | 2008-12-31 |

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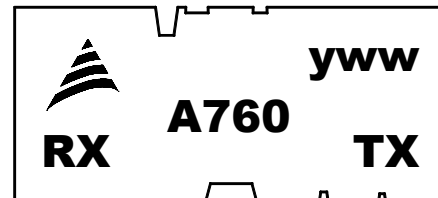
7-Pole Duplexer for WCDMA
Preliminary Data Sheet

B69967N2047A760

Component drawing



marking

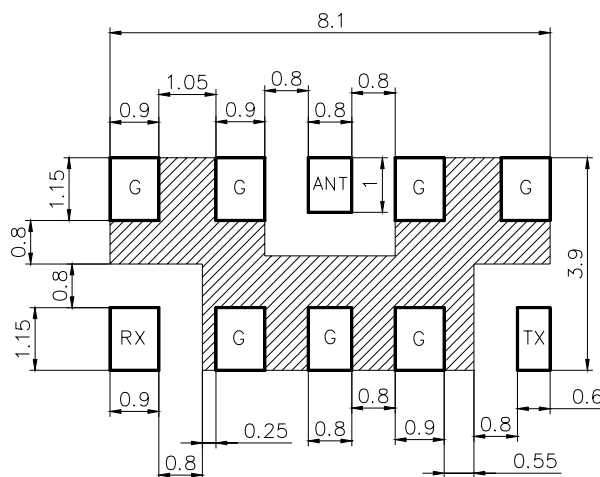


y= calendar year
w= calendar week
e.g.: 427= calendar year 2004,
calendar week 27

*depending in final pressing tool

View from below onto the solder terminals and view from beside

Recommended footprint



TX, RX, ANT, G solder pads



ground area below solder resist with vias
to second ground layer

I/O

connected to lines with an impedance of
50 Ohm

**Standard
condition**

FR4 material
permittivity : 4.4
preferred thickness : 0.3
Vias: Ø0.3mm / mm²
For other thickness
correlation might be necessary

- will be fixed acc. to final pressing tool

| | | | | | | | |
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Preliminary Data Sheet
Characteristics Receiver

| | | min. | typ. | max. | |
|--------------------------------|---------------------|------|------|------|----------|
| Center frequency | f_C | - | 2140 | - | MHz |
| Insertion loss | α_{IL} | | 1.3 | 1.6 | dB |
| Passband | B | 60 | | | MHz |
| Amplitude ripple (peak - peak) | $\Delta\alpha$ | | | 0.9 | dB |
| Standing wave ratio | SWR | | | 1.9 | |
| Impedance | Z | | 50 | | Ω |
| Power | P_{avg} | | | 0.8 | W |
| Attenuation | α | | | | |
| | at DC to 1790 MHz | 35 * | | | dB |
| | at 1790 to 1920 MHz | 30 | | | dB |
| | at 1920 to 1980 MHz | 50 | | | dB |
| | at 1980 to 2025 MHz | 20 | | | dB |
| | at 4030 to 4150 MHz | 23 * | | | dB |
| | at 5950 to 6000 MHz | 33 * | | | dB |

*depending on final pressing tool and final layout

Characteristics Transmitter

| | | min. | typ. | max. | |
|--------------------------------|---------------------|------|------|------|----------|
| Center frequency | f_C | - | 1950 | - | MHz |
| Insertion loss | α_{IL} | | 1.1 | 1.4 | dB |
| Passband | B | 60 | | | MHz |
| Amplitude ripple (peak - peak) | $\Delta\alpha$ | | | 0.6 | dB |
| Standing wave ratio | SWR | | | 1.8 | |
| Impedance | Z | | 50 | | Ω |
| Power | P_{max} | | | 1.0 | W |
| Attenuation | α | | | | |
| | at DC to 1000 MHz | 40 | | | dB |
| | at 2110 to 2170 MHz | 42 | | | dB |
| | at 2400 to 2550 MHz | 40 | | | dB |
| | at 3840 to 3960 MHz | 33 * | | | dB |
| | at 5760 to 5940 MHz | 23 * | | | dB |

*depending on final pressing tool and final layout

Isolation Tx – Rx

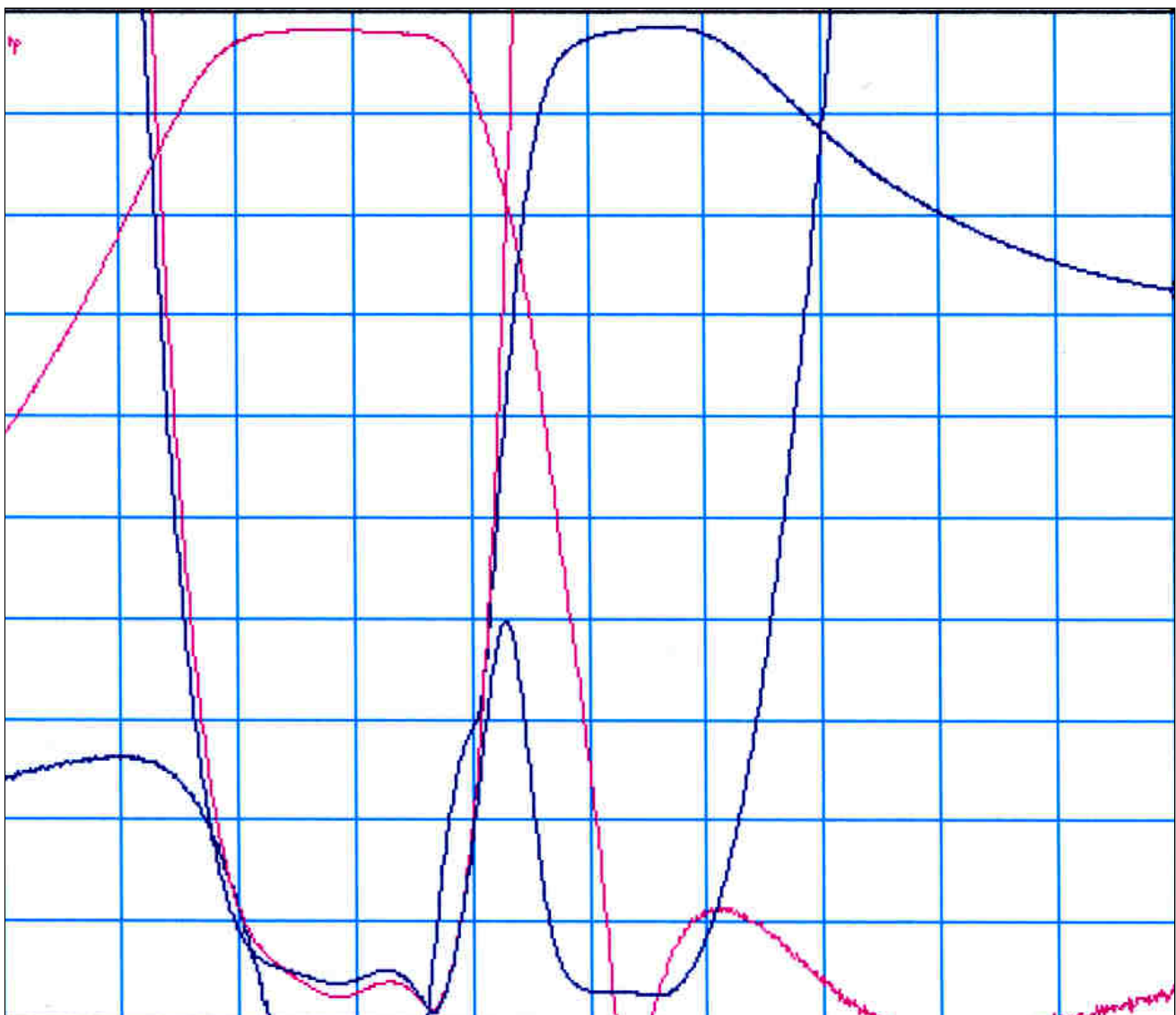
| | | min. | typ. | max. | |
|-------------|---------------------|------|------|------|----|
| Attenuation | α | | | | |
| | at 1920 to 1980 MHz | 50 | | | dB |
| | at 2110 to 2170 MHz | 45 | | | dB |

| | | | | | | | |
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Maximum ratings

| | | |
|----------------------------------|--------------------|----|
| IEC climatic category (IEC 68-1) | - 40/+ 90/56 | |
| Operating temperature | T_{op} -40 / +85 | °C |

Typical passband characteristic

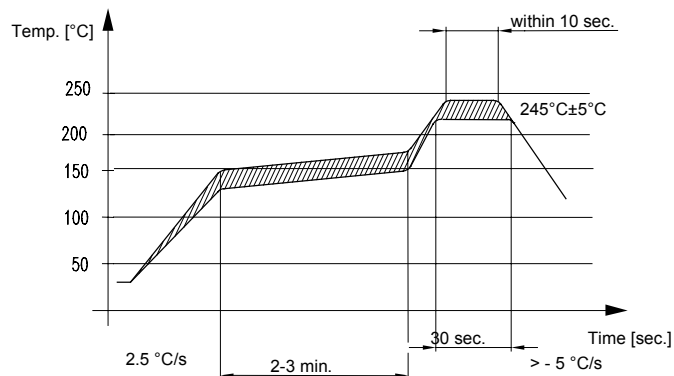
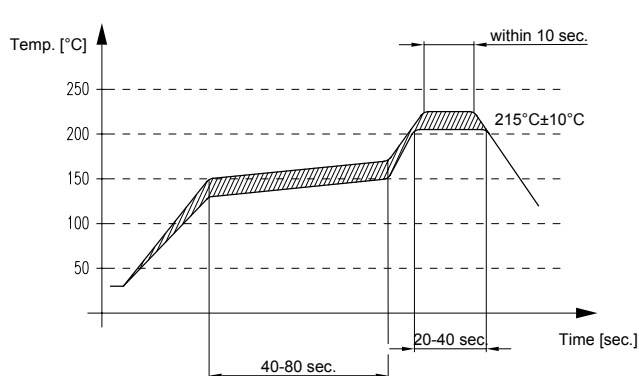


Preliminary Data Sheet
Processing information

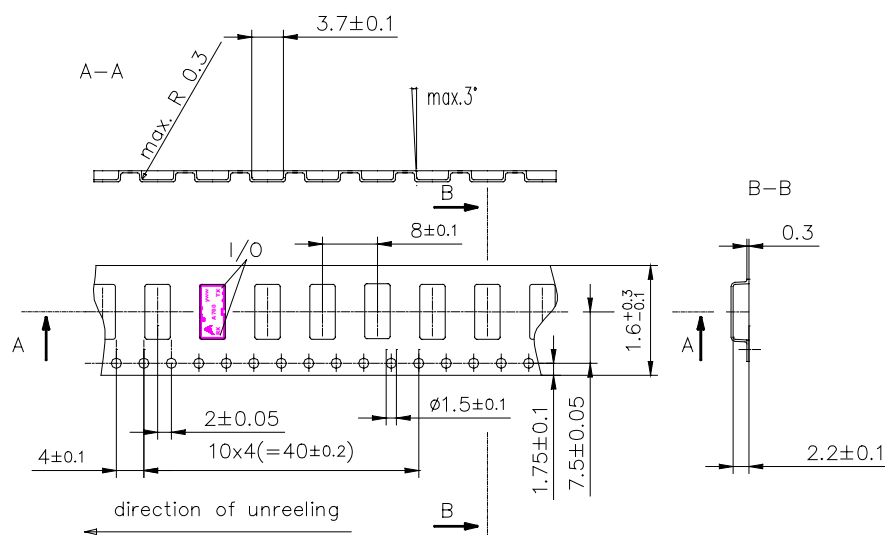
- Wettability to IEC 68-2-58: $\geq 75\%$ (after aging)

Soldering Requirements

| | Profile for eutectic SnPb solder paste | Profile for leadfree solder paste | |
|---|---|---|----------|
| Soldering type | reflow | reflow | |
| Maximum soldering temperature (measuring point on top surface of the component) | 235 (max. 2 sec.) 225 (max. 10 sec.) | 260 (max. 2 sec.) 250 (max. 10 sec.) | °C °C |

Recommended soldering conditions (infrared):

Delivery mode

- Blister tape acc. to IEC 286-3, polyester, grey
- Pieces/tape: 3000



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